

Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

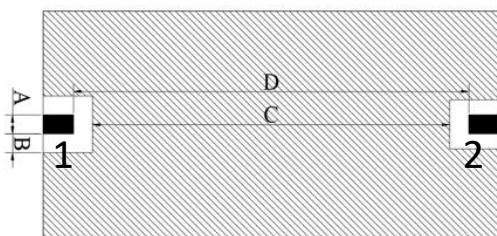
Specifications

NO.	Parameter	SPC
1	Frequency range(MHz)	835-885
2	Insertion Loss (dB)@25°C	≤3.5
3	VSWR	≤1.6
4	Ripple (dB)	≤0.6
5	Attenuation(dBc)	≥35@DC~690MHz
		≥35 @980~2000MHz
6	In/Output Impedance (Ω)	50
7	Power(W)	2W

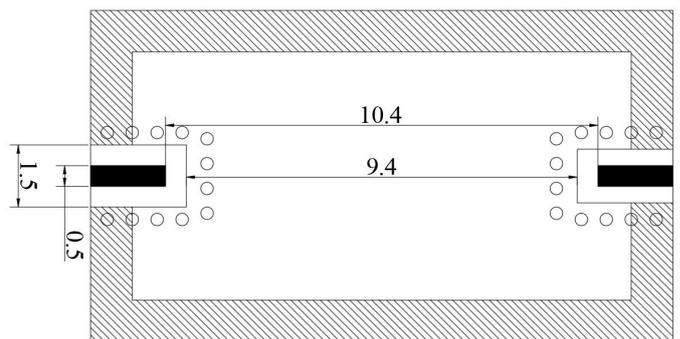
Operating & Storage Condition (Component)
 Operation Temperature Range: -50°C ~ +85°C
 Storage Temperature Range: -50°C~ +85°C

Storage Condition before Soldering (Included packaging material)
 Storage Temperature Range: +5 ~ +40 °C
 Humidity: 30 to 70% relative humidity

Construction

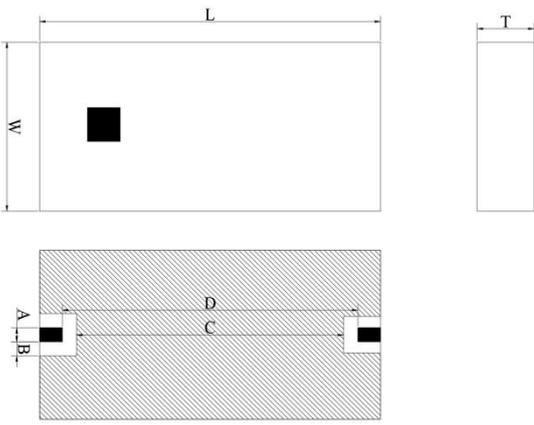


Mounting Considerations

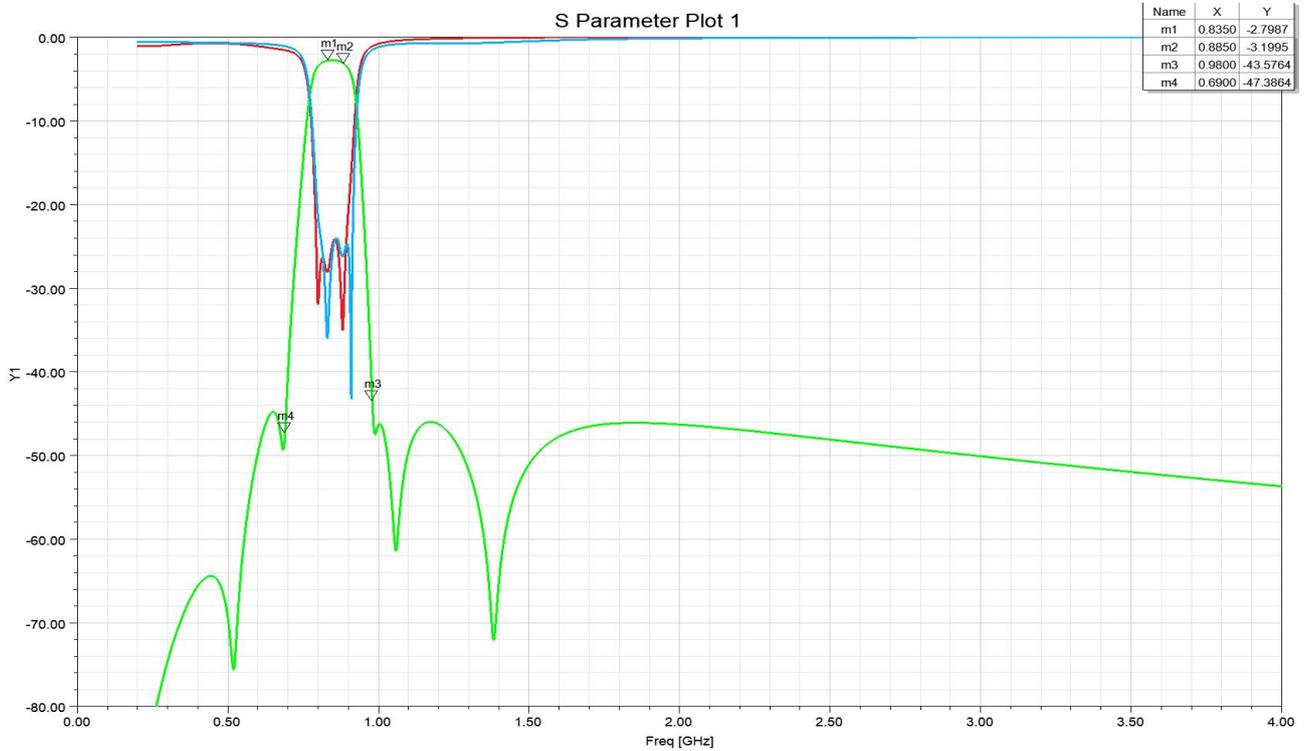


PIN	Connection	PIN	Connection
1	input Port	2	output Port

Dimensions

Figure	Symbol	Dimension (mm)
	L	12.00 ± 0.30
	W	6.00 ± 0.30
	T	2.0 ± 0.20
	A	0.50 ± 0.10
	B	0.50 ± 0.10
	C	9.40 ± 0.30
	D	10.4 ± 0.30

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.